



TET ESTEL AS
ESTONIA

**June
2013**

**Series
TFI133S-400**

High Frequency Inverter grade Capsule Thyristor Type TFI133S-400

Strong distributed amplified gate
and low turn-off time thyristor for
high frequency applications to 20 kHz

Maximum mean on-state current	ITAV 400 A						
Maximum repetitive peak off-state and reverse voltage	UDRM 600 ÷ 1200 V						
Turn-off time	tq 5; 6,3 µs						
UDRM, URRM, V	600	700	800	900	1000	1100	1200
Voltage code	6	7	8	9	10	11	12
Tvj, °C	- 60 ÷ 125						

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	TFI133S-400	Conditions
ITAV	Mean on-state current	A	400 560	Tc=81 °C, Tc=55 °C, 180° half-sine wave, 50 Hz
ITRMS	RMS on-state current	A	628	Tc=81 °C
ITSM	Surge on-state current	kA	6,5 7,0	Tvj=125°C Tvj=25°C
I ² t	Limiting load integral	kA ² s	211 245	Tvj=125°C Tvj=25°C
UDRM, URRM	Repetitive peak off-state and reverse voltage	V	600÷1200	Tj min≤Tvj≤TjM 180° half-sine wave, 50 Hz Gate open
UDSM, URSM	Non-repetitive peak off-state and reverse voltage	V	660÷1300	Tj min≤Tvj≤TjM 180° half-sine wave tp=10 ms, Single pulse Gate open
(di _T /dt) crit	Critical rate of rise of on-state current : non - repetitive repetitive	A/µs	1600 1000	Tvj=125°C ; UD=0,67 UDRM, Gate pulse : 10V, 5 Ω, 1µs rise time, 10 µs
URGM	Peak reverse gate voltage	V	5	Tj min≤Tvj≤TjM
Tstg	Storage temperature	°C	-60÷80	
Tvj	Junction temperature	°C	-60÷125	

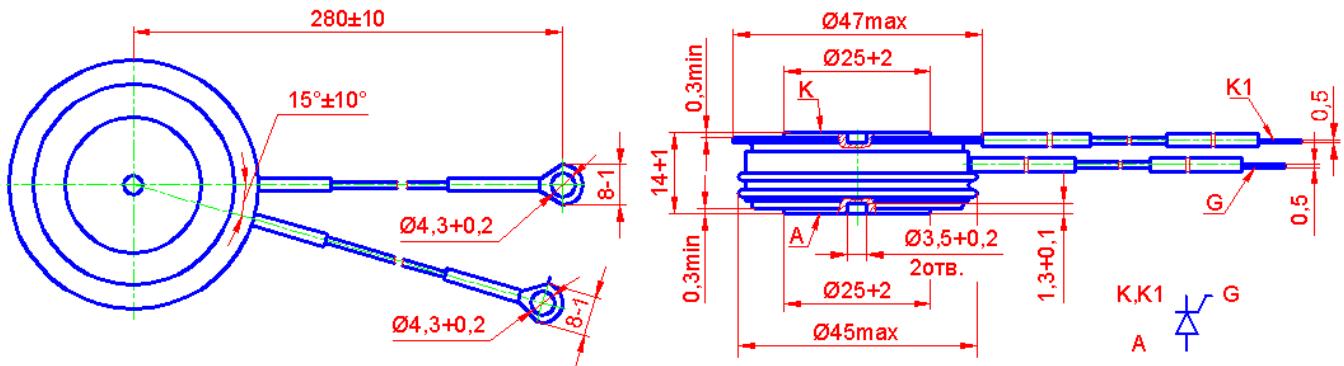
CHARACTERISTICS

UTM	Peak on-state voltage	V	3,0	Tvj=25°C, ITM=3,14 ITAV
UT(TO)	Threshold voltage	V	1,8	Tvj=125°C
RT	On-state slope resistance	mΩ	0,95	1,57 ITAV < IT < 4,71 ITAV
IDRM IRRM	Repetitive peak off-state and reverse current	mA	50 50	Tvj=125°C, UD = UDRM UR= URRM

CHARACTERISTICS					
Symbols and parameters		Units	TFI133S-400	Conditions	
I _L	Latching current	A	12	Tvj=25°C, UD=12V Gate pulse : 10V, 5Ω, 1 μs rise time, 10μs	
I _H	Holding current	A	0,5	Tvj=25°C, UD=12V, Gate open	
UGT	Gate trigger direct voltage	V	2,5 5,0	Tvj=25°C, Tvj=-60°C	UD=12V
IGT	Gate trigger direct current	A	0,4 0,9	Tvj=25°C, Tvj=-60°C	
UGD	Gate non-trigger direct voltage	V	0,25	Tvj=125°C, UD = 0,67 U _{DRM} Direct gate current	
IGD	Gate non-trigger direct current	mA	10		
t _{gd}	Delay time	μs	1,6	Tvj=25°C, UD=500V IT _M = 400 A	
t _{gt}	Turn-on time	μs	2,5	Gate pulse : 10V, 5Ω, 1 μs rise time, 10μs	
t _q	Turn-off time	μs	5,0 ; 6,3 6,3 ; 8,0	Tvj=125°C, IT _M =400 A di _R /dt=10 A/μs, U _R =100V UD = 0,67 U _{DRM} du _D /dt=50 V/μs du _D /dt=200 V/μs	
Q _{rr}	Recovered charge	μC	60		
t _{rr}	Reverse recovery time	μs	1,85		
I _{RRM}	Peak reverse recovery current	A	65		
(dud/dt) _{crit}	Critical rate of rise of off-state voltage	V/μs	500 1000	Tvj=125°C, UD = 0,67 U _{DRM} Gate open	
R _{thjc}	Thermal resistance junction to case	°C/W	0,04	Direct current, double side cooled	

ORDERING									
	TFI	133	S	400	10	7	C4	3	
	1	2	3	4	5	6	7	8	

1. Fast thyristor with interdigitated gate structure.
2. Design version.
3. Strong distributed amplified gate
4. Mean on-state current, A.
5. Voltage code (10=1000V).
6. Critical rate of rise of off-state voltage ($6 \geq 500 \text{ V/}\mu\text{s}$, $7 \geq 1000 \text{ V/}\mu\text{s}$).
7. Group of turn-off time ($\text{du}_D/\text{dt}=50 \text{ V/}\mu\text{s}$, $\text{C}4 \leq 6,3 \mu\text{s}$, $\text{E}4 \leq 5 \mu\text{s}$).
8. Group of turn-on time ($3 \leq 2,5 \mu\text{s}$).



Mounting force : 9÷12 kN
Weight : 120 grams